

Electronic Patent Application Fee Transmittal

Application Number:	10787368			
Filing Date:	26-Feb-2004			
Title of Invention:	METHOD OF FORMING AN UNDERLAYER OF A BI-LAYER RESIST FILM AND METHOD OF FABRICATING A SEMICONDUCTOR DEVICE USING THE SAME			
First Named Inventor/Applicant Name:	Hyun-Woo Kim			
Filer:	Frank Chau			
Attorney Docket Number:	8028-42 (SPX200304-0017US			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1440	1440
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Printed copy of patent - no color	8001	2	3	6
Total in USD (\$)				1746